



SBR0220LP

#### 0.2A SBR SUPER BARRIER RECTIFIER

#### Features

- Low Leakage Current
- Patented Super Barrier Rectifier Technology
- Excellent High Temperature Stability
- Soft, Fast Switching Capability
- +150°C Operating Junction Temperature
- Lead Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Molding (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability



Top View

#### **Mechanical Data**

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @
- Weight: 0.001 grams (Approximate)



Bottom View

### Ordering Information (Note 4)

Part Number	Case	Packaging
SBR0220LP-7	X1-DFN1006-2	3,000/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

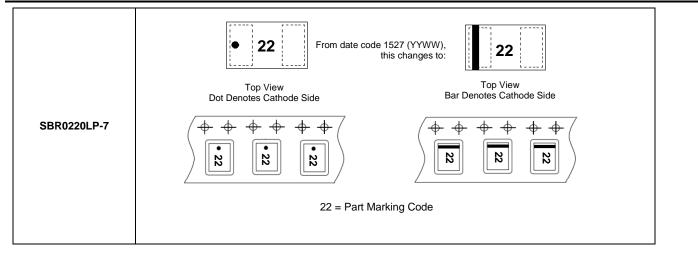
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

Notes:





# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> Vrwm V <sub>RM</sub>	20	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	V
Average Rectified Output Current (See Figure 1)	lo	0.2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	5.0	A

#### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 5) Thermal Resistance Junction to Ambient (Note 6)	$R_{ heta JS} \ R_{ heta} JA$	17 304	°C/W
Operating and Storage Temperature Range	TJ, T <sub>STG</sub>	-65 to +150	°C

#### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	20	-	-	V	I <sub>R</sub> = 400μA
Forward Voltage Drop	V <sub>F</sub>	-	0.38 0.30 0.44 0.38	0.42 0.33 0.48 0.41	V	$\begin{split} I_{F} &= 0.1A, \ T_{J} = +25^{\circ}C \\ I_{F} &= 0.1A, \ T_{J} = +150^{\circ}C \\ I_{F} &= 0.2A, \ T_{J} = +25^{\circ}C \\ I_{F} &= 0.2A, \ T_{J} = +150^{\circ}C \end{split}$
Leakage Current (Note 7)	I <sub>R</sub>	-	2 0.43	50 1.3		V <sub>R</sub> = 20V, T <sub>J</sub> = +25°C V <sub>R</sub> = 20V, T <sub>J</sub> = +150°C

 Theoretical R<sub>0JS</sub> calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 FR-4 PCB, 2oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
 Short duration pulse test used to minimize self-heating effect. Notes:



0.6

20

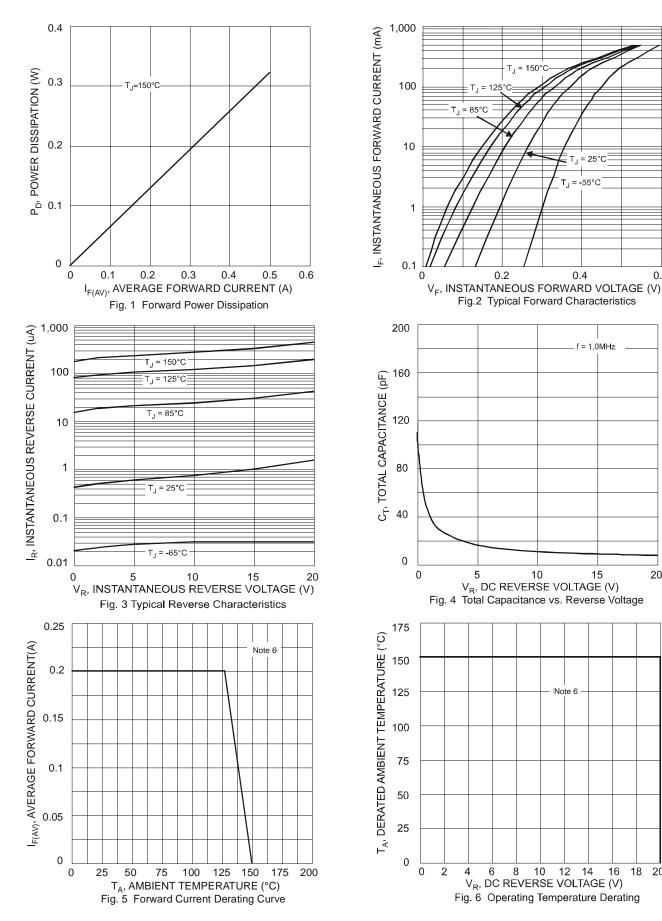
= 25°C

 $T_J = -55^{\circ}C$ 

0.4

Note 6

f = 1.0MHz

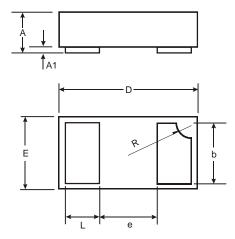


18 20



## **Package Outline Dimensions**

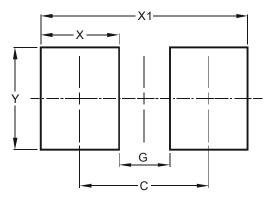
Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



X1-DFN1006-2					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0	0.05	0.03		
b	0.45	0.55	0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
e	-	-	0.40		
L	0.20	0.30	0.25		
R	0.05	0.15	0.10		
All Dimensions in mm					

### **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Y	0.70



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